

# Semiconductor Die with Solderable Metal System Allowing Direct Surface Mounting to Printed Circuit Boards

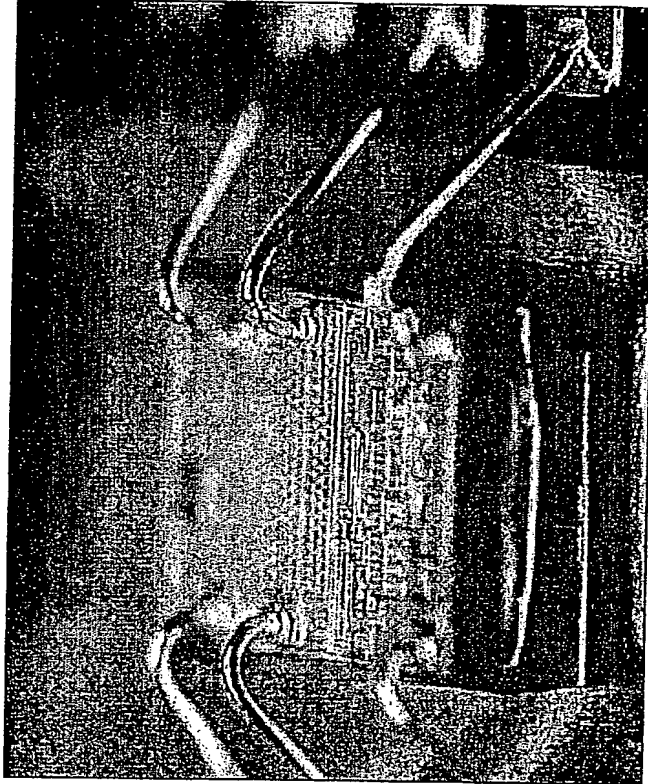


Figure 1. Example of Wire Bonding Used to Form the Electrical Connections to the Semiconductor Die

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Solder Ball

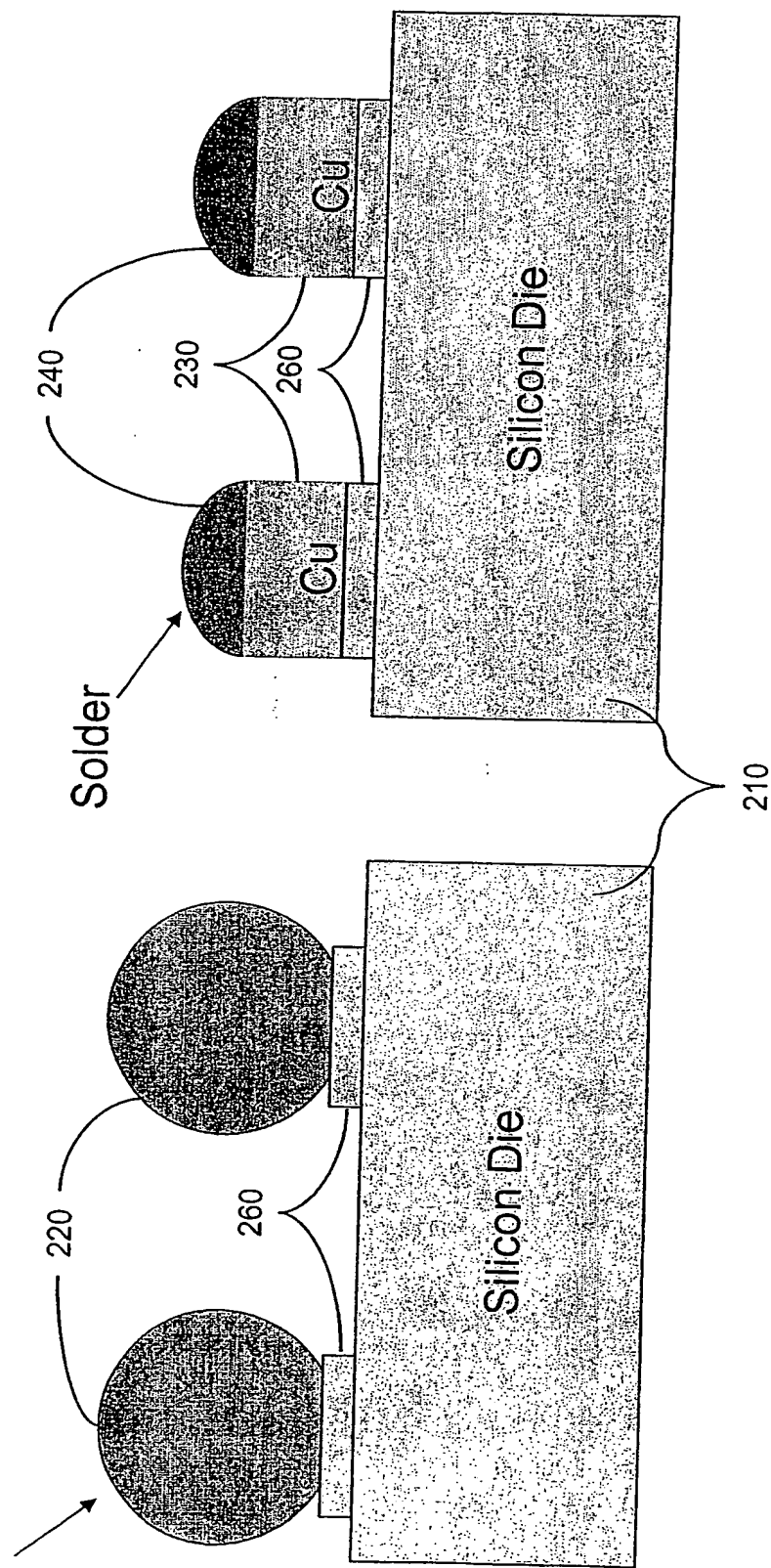
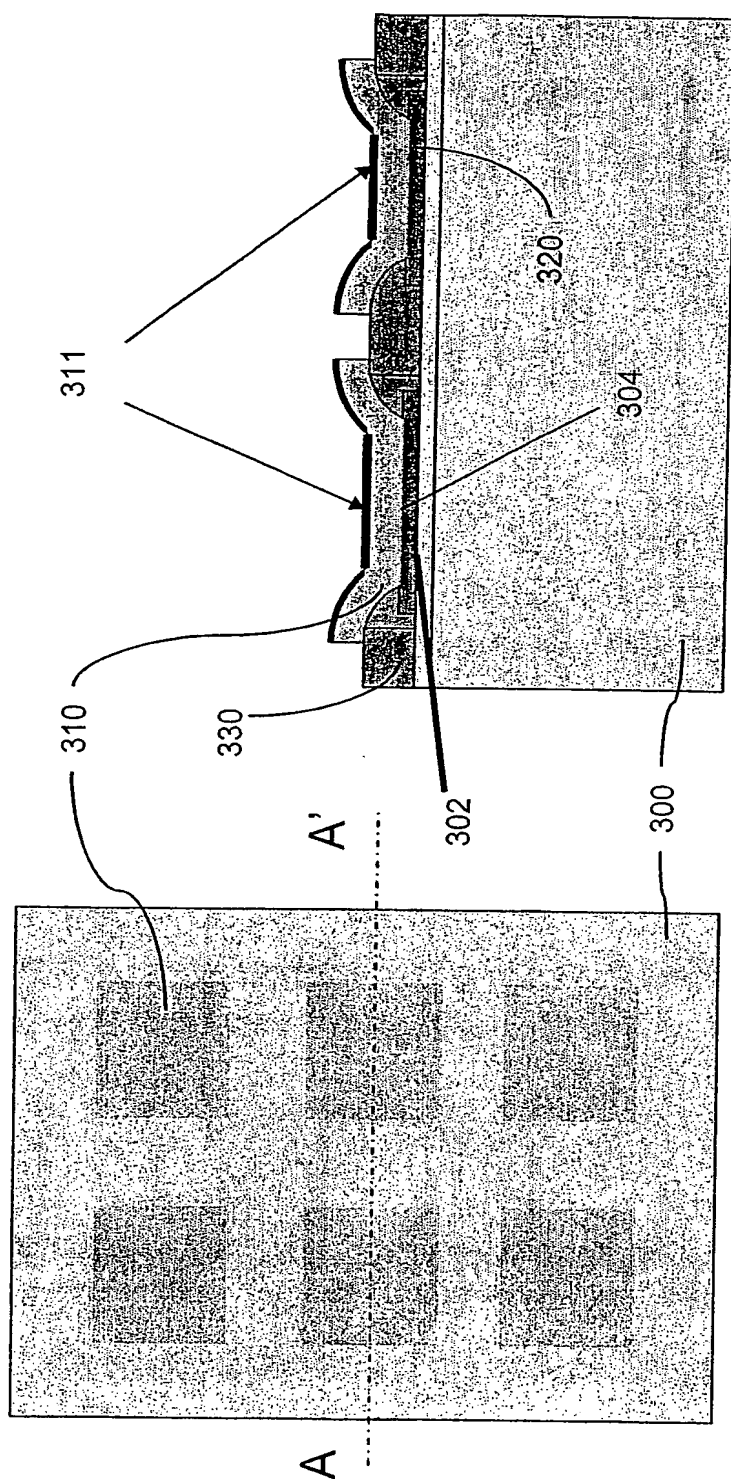


Figure 2. Typical Flip Chip Wafer Bumping Packages

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## Top View

Cross-Sectional View (A-A')

Figure 3. Die with Solderable Metal Contacts for Direct Printed Circuit Board Mounting

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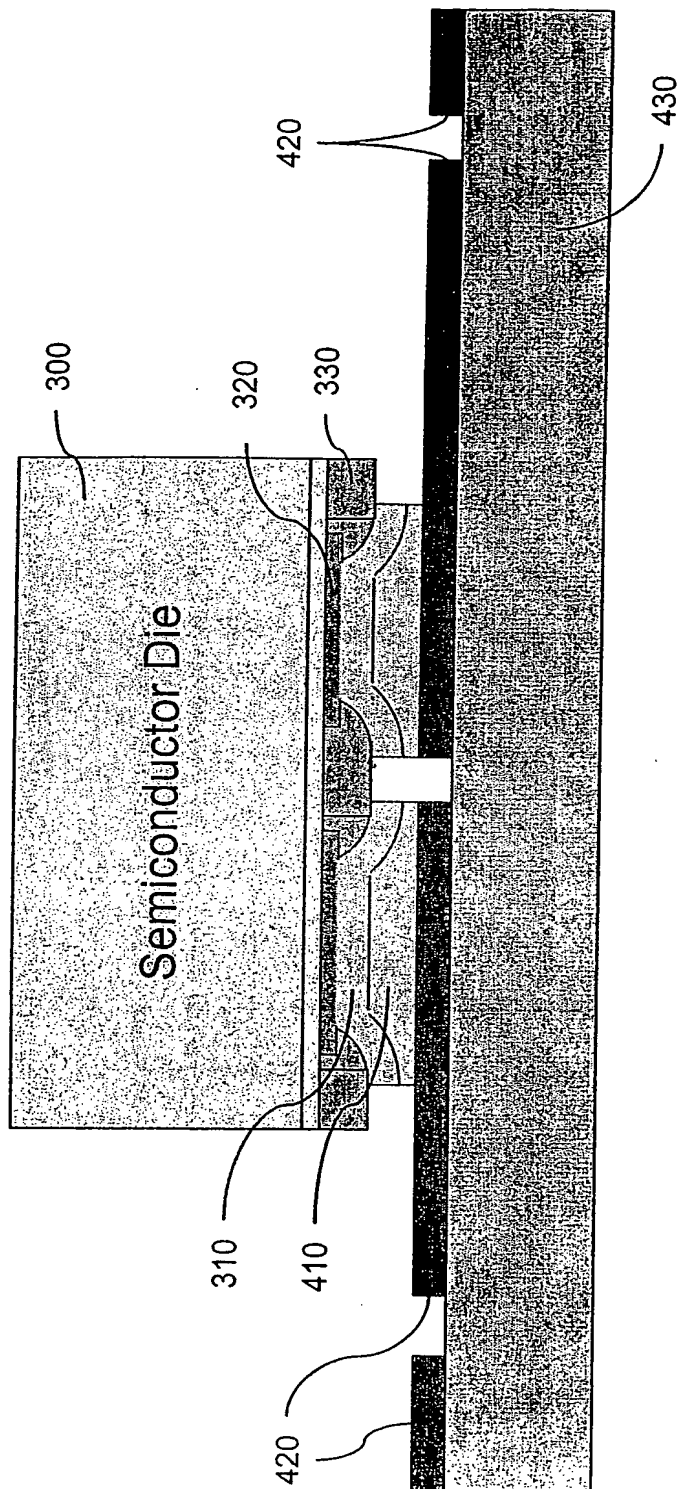


Figure 4. Illustration of Die with Solderable Electrical Contacts Mounted on Printed Circuit Board